

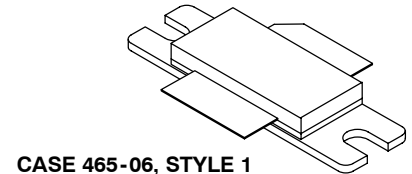
The RF MOSFET Line
RF Power Field Effect Transistors
N-Channel Enhancement-Mode Lateral MOSFETs

Designed for W-CDMA base station applications with frequencies from 2110 to 2170 MHz. Suitable for TDMA, CDMA and multicarrier amplifier applications. To be used in Class AB for PCN - PCS/cellular radio and WLL applications.

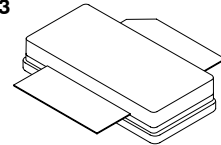
- Typical 2-carrier W-CDMA Performance for $V_{DD} = 28$ Volts, $I_{DQ} = 1000$ mA, $f_1 = 2135$ MHz, $f_2 = 2145$ MHz, Channel Bandwidth = 3.84 MHz, Adjacent Channels Measured over 3.84 MHz BW @ $f_1 - 5$ MHz and $f_2 + 5$ MHz, Distortion Products Measured over a 3.84 MHz BW @ $f_1 - 10$ MHz and $f_2 + 10$ MHz, Peak/Avg. = 8.3 dB @ 0.01% Probability on CCDF.
 - Output Power — 19 Watts Avg.
 - Power Gain — 13.6 dB
 - Efficiency — 23%
 - IM3 — -37.5 dBc
 - ACPR — -41 dBc
- Internally Matched, Controlled Q, for Ease of Use
- High Gain, High Efficiency and High Linearity
- Integrated ESD Protection
- Designed for Maximum Gain and Insertion Phase Flatness
- Capable of Handling 5:1 VSWR, @ 28 Vdc, 2170 MHz, 90 Watts CW Output Power
- Excellent Thermal Stability
- Characterized with Series Equivalent Large-Signal Impedance Parameters
- Available with Low Gold Plating Thickness on Leads. L Suffix Indicates 40 μ Nominal.
- In Tape and Reel. R3 Suffix = 250 Units per 56 mm, 13 inch Reel.

MRF21085R3
MRF21085SR3
MRF21085LSR3

2170 MHz, 90 W, 28 V
LATERAL N-CHANNEL
RF POWER MOSFETs



CASE 465-06, STYLE 1
NI-780
MRF21085R3



CASE 465A-06, STYLE 1
NI-780S
MRF21085SR3, MRF21085LSR3

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|-----------|--------------|------------------------------|
| Drain-Source Voltage | V_{DSS} | 65 | Vdc |
| Gate-Source Voltage | V_{GS} | -0.5, +15 | Vdc |
| Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25 $^\circ\text{C}$ | P_D | 224 1.28 | Watts W/ $^\circ\text{C}$ |
| Storage Temperature Range | T_{stg} | - 65 to +150 | $^\circ\text{C}$ |
| Operating Junction Temperature | T_J | 200 | $^\circ\text{C}$ |

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value (1) | Unit |
|--------------------------------------|-----------------|-----------|---------------------------|
| Thermal Resistance, Junction to Case | $R_{\theta JC}$ | 0.78 | $^\circ\text{C}/\text{W}$ |

ESD PROTECTION CHARACTERISTICS

| Test Conditions | Class |
|------------------|--------------|
| Human Body Model | 1 (Minimum) |
| Machine Model | M3 (Minimum) |

(1) Refer to AN1955/D, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.motorola.com/semiconductors/rf>. Select Documentation/Application Notes - AN1955.

NOTE - CAUTION - MOS devices are susceptible to damage from electrostatic charge. Reasonable precautions in handling and packaging MOS devices should be observed.

Freescale Semiconductor, Inc.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|----------------|--------|-----|-----|-----|------|
|----------------|--------|-----|-----|-----|------|

OFF CHARACTERISTICS

| | | | | | |
|--|----------------------|----|---|----|------|
| Drain-Source Breakdown Voltage (V _{GS} = 0 Vdc, I _D = 100 μAdc) | V _{(BR)DSS} | 65 | — | — | Vdc |
| Zero Gate Voltage Drain Current (V _{DS} = 28 Vdc, V _{GS} = 0 Vdc) | I _{DSS} | — | — | 10 | μAdc |
| Gate-Source Leakage Current (V _{GS} = 5 Vdc, V _{DS} = 0 Vdc) | I _{GSS} | — | — | 1 | μAdc |

ON CHARACTERISTICS (DC)

| | | | | | |
|--|---------------------|---|------|------|-----|
| Gate Threshold Voltage (V _{DS} = 10 Vdc, I _D = 200 μAdc) | V _{GS(th)} | 2 | — | 4 | Vdc |
| Gate Quiescent Voltage (V _{DS} = 28 Vdc, I _D = 1000 mAdc) | V _{GS(Q)} | 3 | 3.9 | 5 | Vdc |
| Drain-Source On-Voltage (V _{GS} = 10 Vdc, I _D = 2 Adc) | V _{DS(on)} | — | 0.18 | 0.21 | Vdc |
| Forward Transconductance (V _{DS} = 10 Vdc, I _D = 2 Adc) | g _{fs} | — | 6 | — | S |

DYNAMIC CHARACTERISTICS (1)

| | | | | | |
|--|------------------|---|-----|---|----|
| Reverse Transfer Capacitance (V _{DS} = 28 Vdc, V _{GS} = 0, f = 1.0 MHz) | C _{rss} | — | 3.6 | — | pF |
|--|------------------|---|-----|---|----|

FUNCTIONAL TESTS (In Motorola Test Fixture, 50 ohm system) 2-carrier W-CDMA, 3.84 MHz Channel Bandwidth Carriers, ACPR and IM3 measured in 3.84 MHz Bandwidth. Peak/Avg. = 8.3 dB @ 0.01% Probability on CCDF.

| | | | | | |
|---|-----------------|--|-------|-----|-----|
| Common-Source Amplifier Power Gain (V _{DD} = 28 Vdc, P _{out} = 19 W Avg., I _{DQ} = 1000 mA, f ₁ = 2112.5 MHz, f ₂ = 2122.5 MHz and f ₁ = 2157.5 MHz, f ₂ = 2167.5 MHz) | G _{ps} | 12 | 13.6 | — | dB |
| Drain Efficiency (V _{DD} = 28 Vdc, P _{out} = 19 W Avg., I _{DQ} = 1000 mA, f ₁ = 2112.5 MHz, f ₂ = 2122.5 MHz and f ₁ = 2157.5 MHz, f ₂ = 2167.5 MHz) | η | 20 | 23 | — | % |
| Third Order Intermodulation Distortion (V _{DD} = 28 Vdc, P _{out} = 19 W Avg., I _{DQ} = 1000 mA, f ₁ = 2112.5 MHz, f ₂ = 2122.5 MHz and f ₁ = 2157.5 MHz, f ₂ = 2167.5 MHz; IM3 measured over 3.84 MHz BW at f ₁ -10 MHz and f ₂ +10 MHz referenced to carrier channel power.) | IM3 | — | -37.5 | -35 | dBc |
| Adjacent Channel Power Ratio (V _{DD} = 28 Vdc, P _{out} = 19 W Avg., I _{DQ} = 1000 mA, f ₁ = 2112.5 MHz, f ₂ = 2122.5 MHz and f ₁ = 2157.5 MHz, f ₂ = 2167.5 MHz; ACPR measured over 3.84 MHz at f ₁ -5 MHz and f ₂ +5 MHz.) | ACPR | — | -41 | -38 | dBc |
| Input Return Loss (V _{DD} = 28 Vdc, P _{out} = 19 W Avg., I _{DQ} = 1000 mA, f ₁ = 2112.5 MHz, f ₂ = 2122.5 MHz and f ₁ = 2157.5 MHz, f ₂ = 2167.5 MHz) | IRL | — | -12 | -9 | dB |
| Output Mismatch Stress (V _{DD} = 28 Vdc, P _{out} = 90 W CW, I _{DQ} = 1000 mA, f = 2170 MHz VSWR = 5:1, All Phase Angles at Frequency of Tests) | Ψ | No Degradation In Output Power Before and After Test | | | |

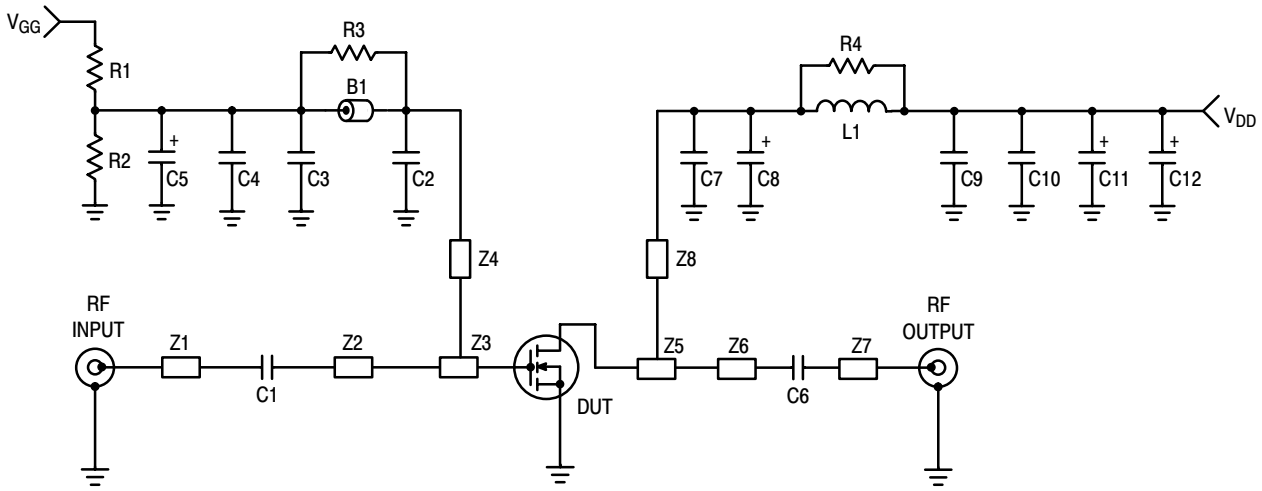
(1) Part is internally matched both on input and output.

(continued)

Freescale Semiconductor, Inc.

ELECTRICAL CHARACTERISTICS — continued ($T_C = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|--|----------|-----|------|-----|------|
| FUNCTIONAL TESTS (In Motorola Test Fixture, 50 ohm system) (continued) | | | | | |
| Two-Tone Common-Source Amplifier Power Gain ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 90\text{ W PEP}$, $I_{DQ} = 1000\text{ mA}$, $f_1 = 2110\text{ MHz}$, $f_2 = 2120\text{ MHz}$ and $f_1 = 2160\text{ MHz}$, $f_2 = 2170\text{ MHz}$) | G_{ps} | — | 13.6 | — | dB |
| Two-Tone Drain Efficiency ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 90\text{ W PEP}$, $I_{DQ} = 1000\text{ mA}$, $f_1 = 2110\text{ MHz}$, $f_2 = 2120\text{ MHz}$ and $f_1 = 2160\text{ MHz}$, $f_2 = 2170\text{ MHz}$) | η | — | 36 | — | % |
| Two-Tone Intermodulation Distortion ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 90\text{ W PEP}$, $I_{DQ} = 1000\text{ mA}$, $f_1 = 2110\text{ MHz}$, $f_2 = 2120\text{ MHz}$ and $f_1 = 2160\text{ MHz}$, $f_2 = 2170\text{ MHz}$) | IMD | — | -31 | — | dBc |
| Input Return Loss ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 90\text{ W PEP}$, $I_{DQ} = 1000\text{ mA}$, $f_1 = 2110\text{ MHz}$, $f_2 = 2120\text{ MHz}$ and $f_1 = 2160\text{ MHz}$, $f_2 = 2170\text{ MHz}$) | IRL | — | -12 | — | dB |
| P_{out} , 1 dB Compression Point ($V_{DD} = 28\text{ Vdc}$, $I_{DQ} = 1000\text{ mA}$, $f = 2170\text{ MHz}$) | P1dB | — | 100 | — | W |



| | | | |
|----|----------------------------|-------|---|
| Z1 | 0.750" x 0.084" Microstrip | Board | 0.030" Glass Teflon®, Keene GX-0300-55-22, $\epsilon_r = 2.55$ |
| Z2 | 1.015" x 0.084" Microstrip | PCB | Etched Circuit Boards |
| Z3 | 0.480" x 0.800" Microstrip | | MRF21085 Rev. 3, CMR |
| Z4 | 0.750" x 0.050" Microstrip | | |
| Z5 | 0.610" x 0.800" Microstrip | | |
| Z6 | 0.885" x 0.084" Microstrip | | |
| Z7 | 0.720" x 0.084" Microstrip | | |
| Z8 | 0.800" x 0.070" Microstrip | | |

Figure 1. MRF21085 Test Circuit Schematic

Table 1. MRF21085 Test Circuit Component Designations and Values

| Designators | Description |
|-------------|--|
| B1 | Short Ferrite Bead, Fair Rite, #2743019447 |
| C1, C6 | 43 pF Chip Capacitors, ATC #100B430JCA500X |
| C2 | 10 pF Chip Capacitor, ATC #100B100JCA500X |
| C3, C9 | 1000 pF Chip Capacitors, ATC #100B102JCA500X |
| C4, C10 | 0.1 μ F Chip Capacitors, Kemet #CDR33BX104AKWS |
| C5 | 1.0 μ F Tantalum Chip Capacitor, Kemet #T491C105M050 |
| C7 | 2.7 pF Chip Capacitor, ATC #100B2R7JCA500X |
| C8 | 10 μ F Tantalum Chip Capacitor, Kemet #T495X106K035AS4394 |
| C11, C12 | 22 μ F Tantalum Chip Capacitors, Kemet #T491X226K035AS4394 |
| L1 | 1 Turn, #20 AWG, 0.100" ID, Motorola |
| N1, N2 | Type N Flange Mounts, Omni Spectra #3052-1648-10 |
| R1 | 1.0 k Ω , 1/8 W Chip Resistor |
| R2 | 180 k Ω , 1/8 W Chip Resistor |
| R3, R4 | 10 Ω , 1/8 W Chip Resistors |

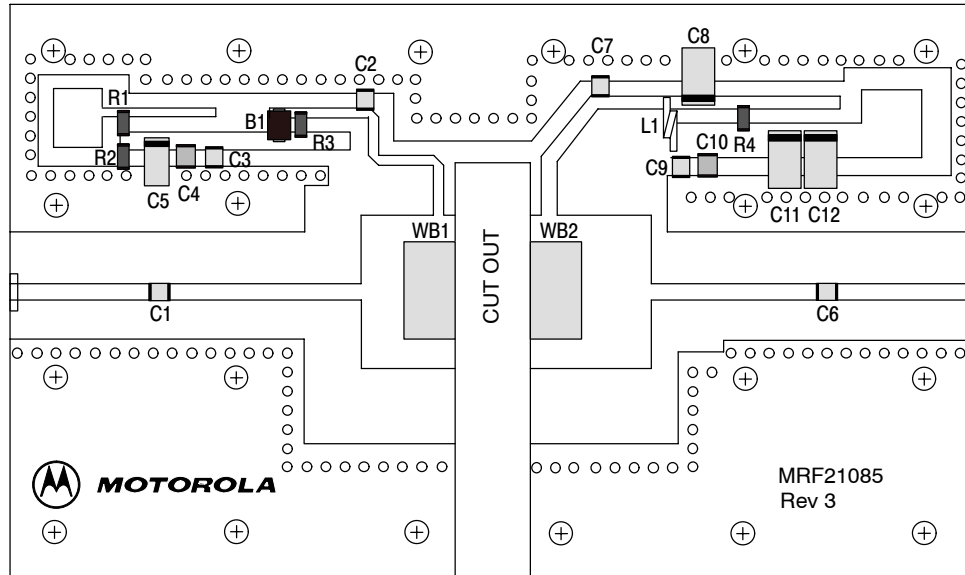


Figure 2. MRF21085 Test Circuit Component Layout

TYPICAL CHARACTERISTICS

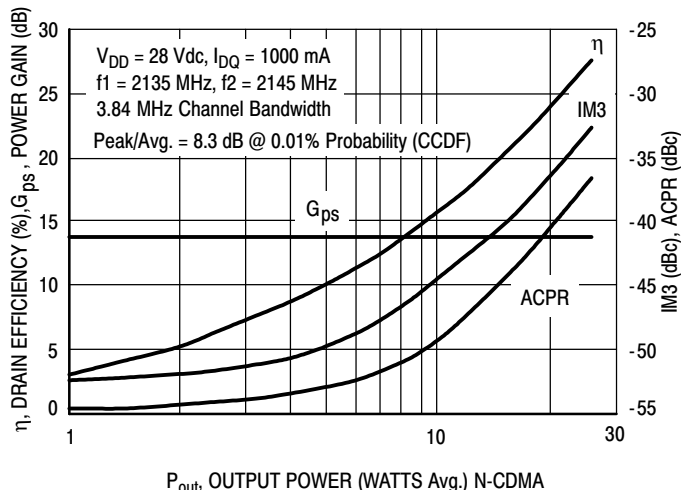


Figure 3. 2-Carrier W-CDMA ACPR, IM3, Power Gain and Drain Efficiency versus Output Power

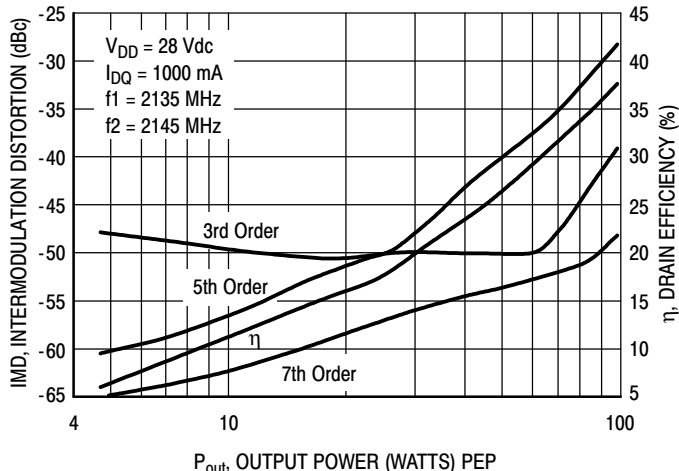


Figure 4. Intermodulation Distortion Products versus Output Power

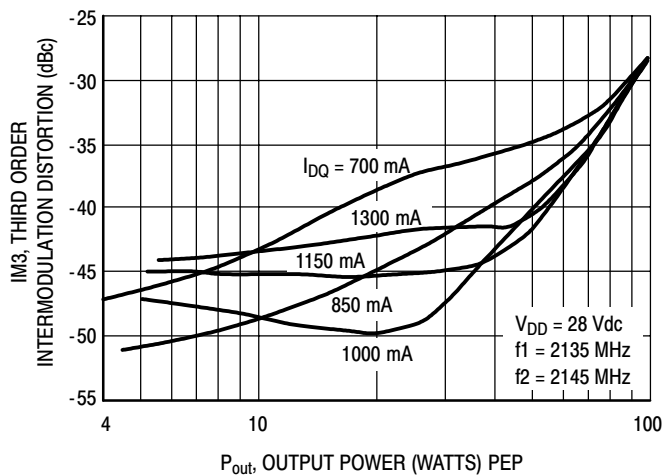


Figure 5. Third Order Intermodulation Distortion versus Output Power

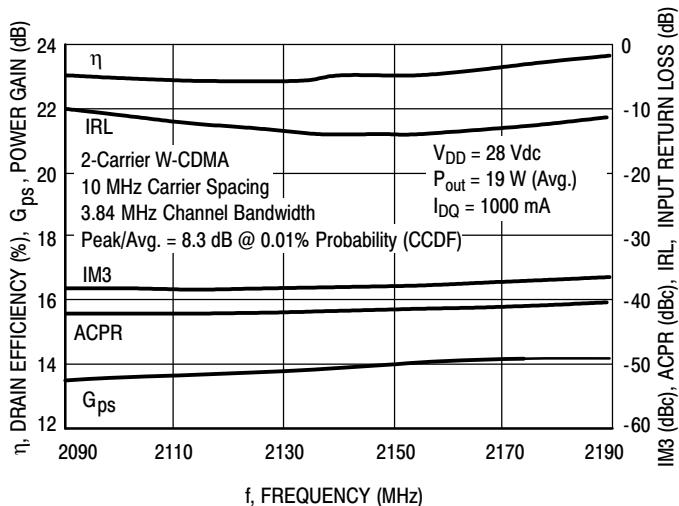


Figure 6. 2-Carrier W-CDMA Broadband Performance

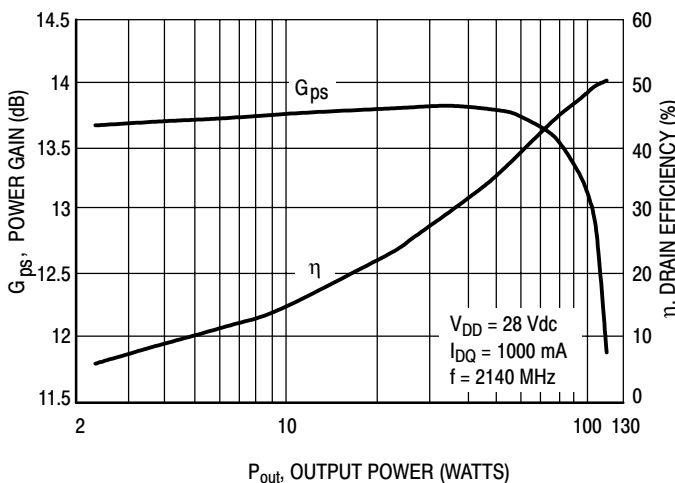


Figure 7. CW Performance

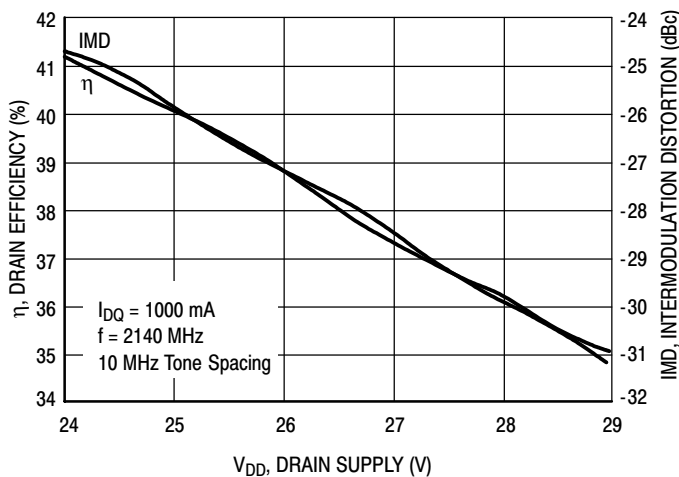


Figure 8. Two-Tone Intermodulation Distortion and Drain Efficiency versus Drain Supply

TYPICAL CHARACTERISTICS

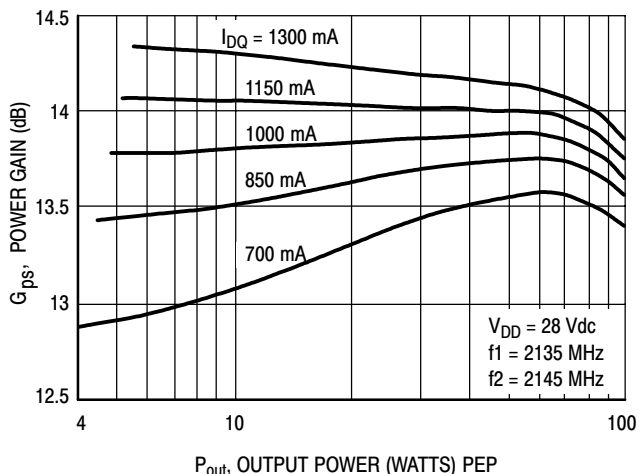


Figure 9. Two-Tone Power Gain versus Output Power

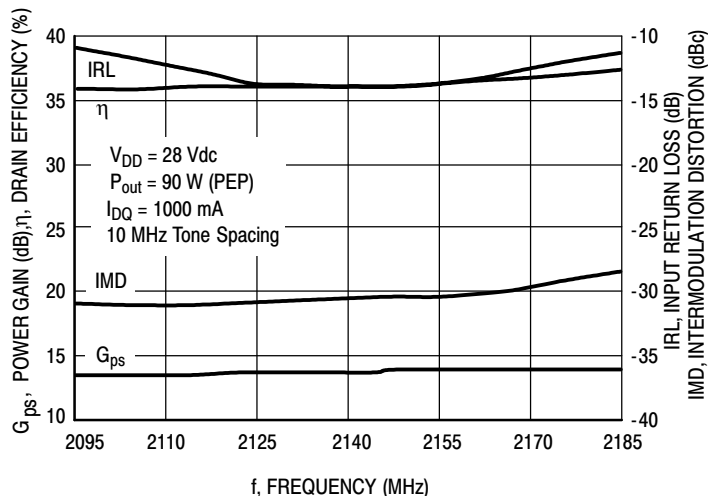


Figure 10. Two-Tone Broadband Performance

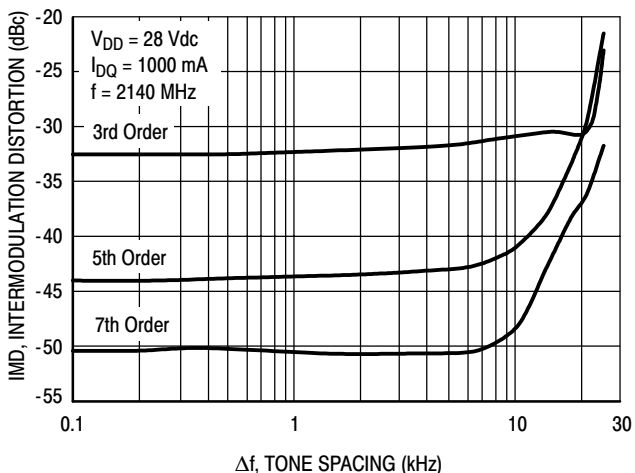


Figure 11. Intermodulation Distortion Products versus Two-Tone Spacing

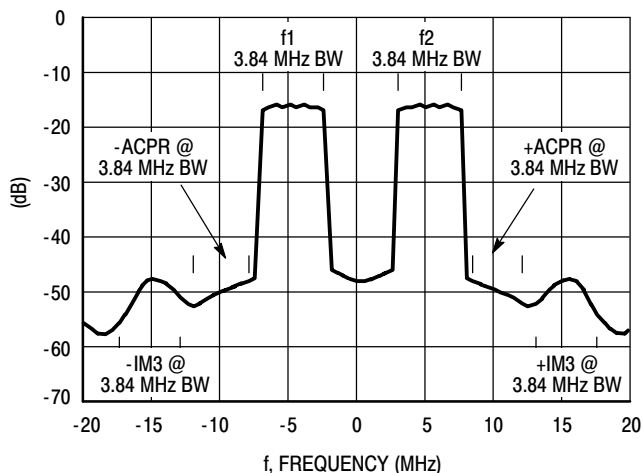
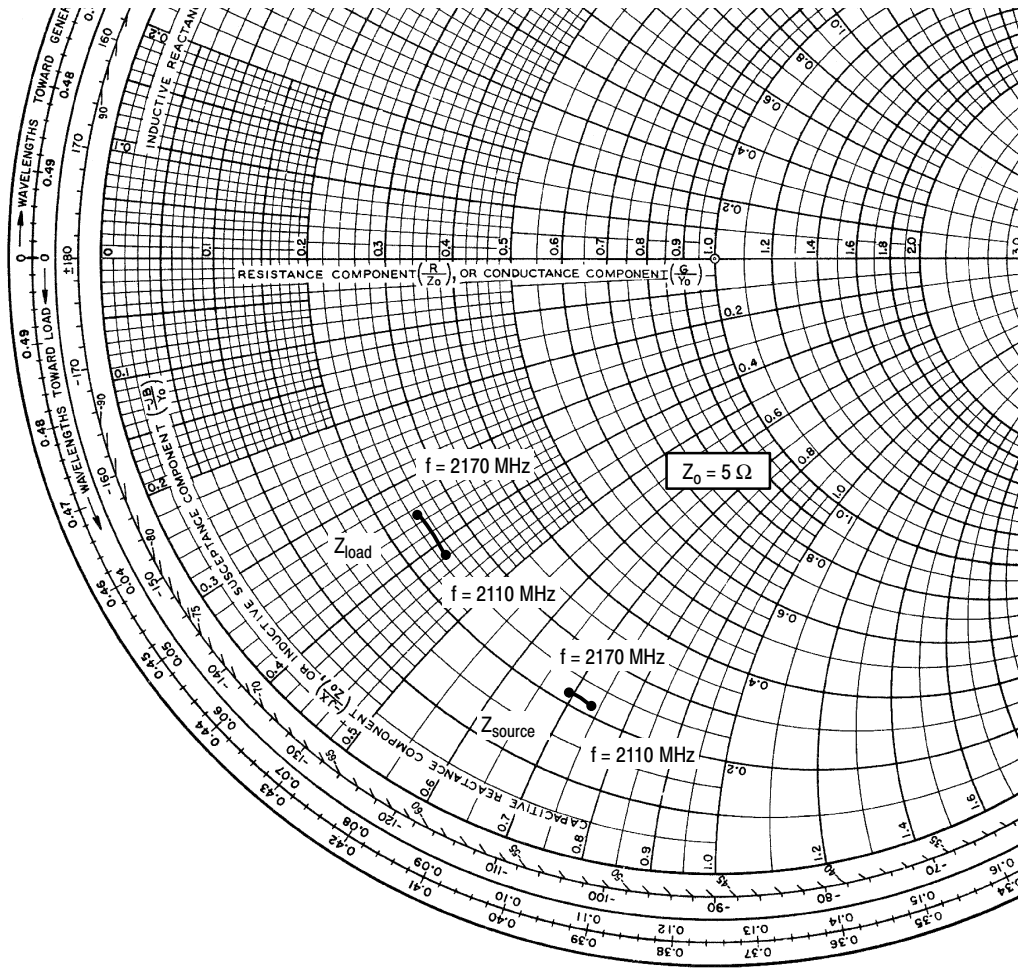


Figure 12. 2-Carrier W-CDMA Spectrum



$V_{DD} = 28 \text{ V}$, $I_{DQ} = 1000 \text{ mA}$, $P_{out} = 19 \text{ W Avg.}$

| f MHz | Z_{source} Ω | Z_{load} Ω |
|----------|--------------------------|------------------------|
| 2110 | $1.10 - j3.71$ | $1.23 - j2.10$ |
| 2140 | $1.11 - j3.57$ | $1.26 - j1.92$ |
| 2170 | $1.12 - j3.40$ | $1.25 - j1.76$ |

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

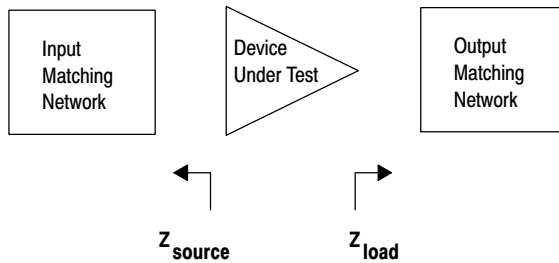


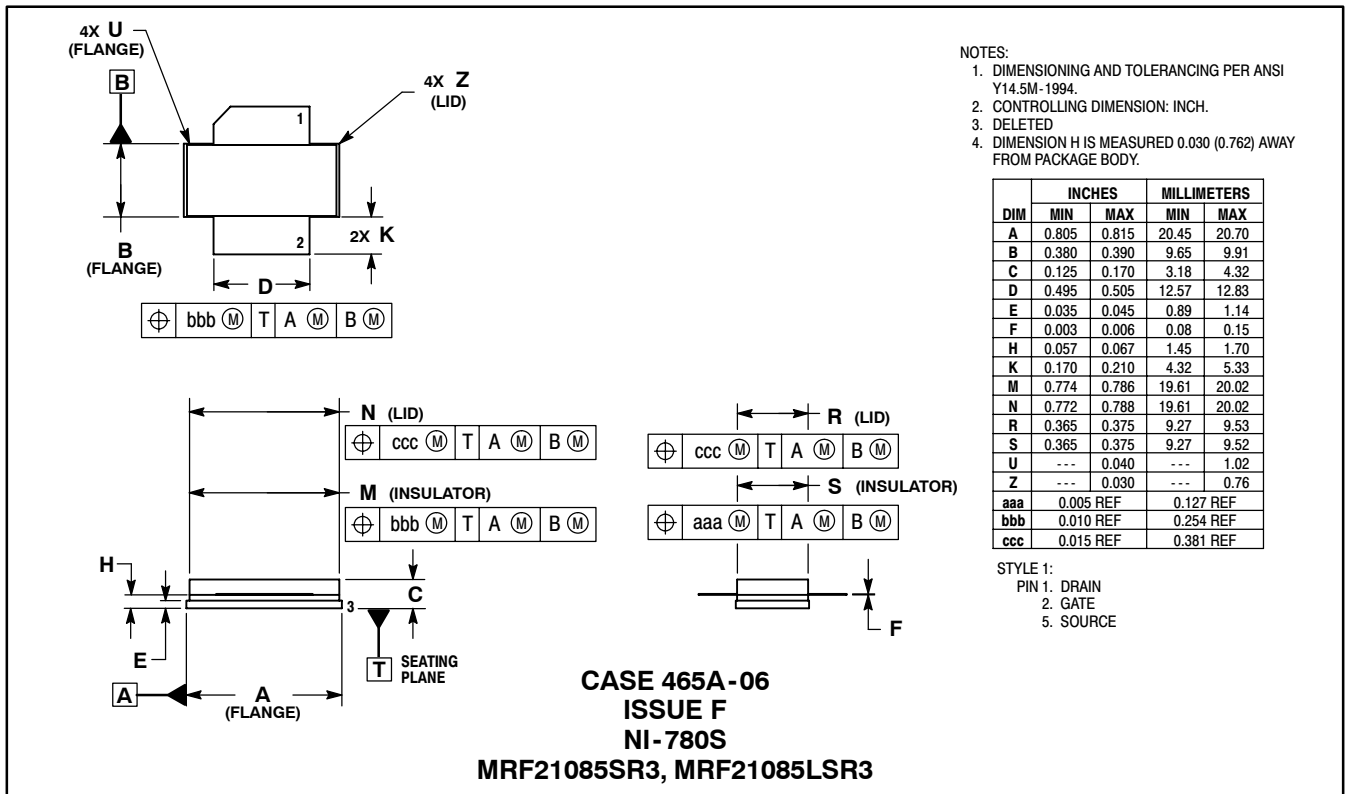
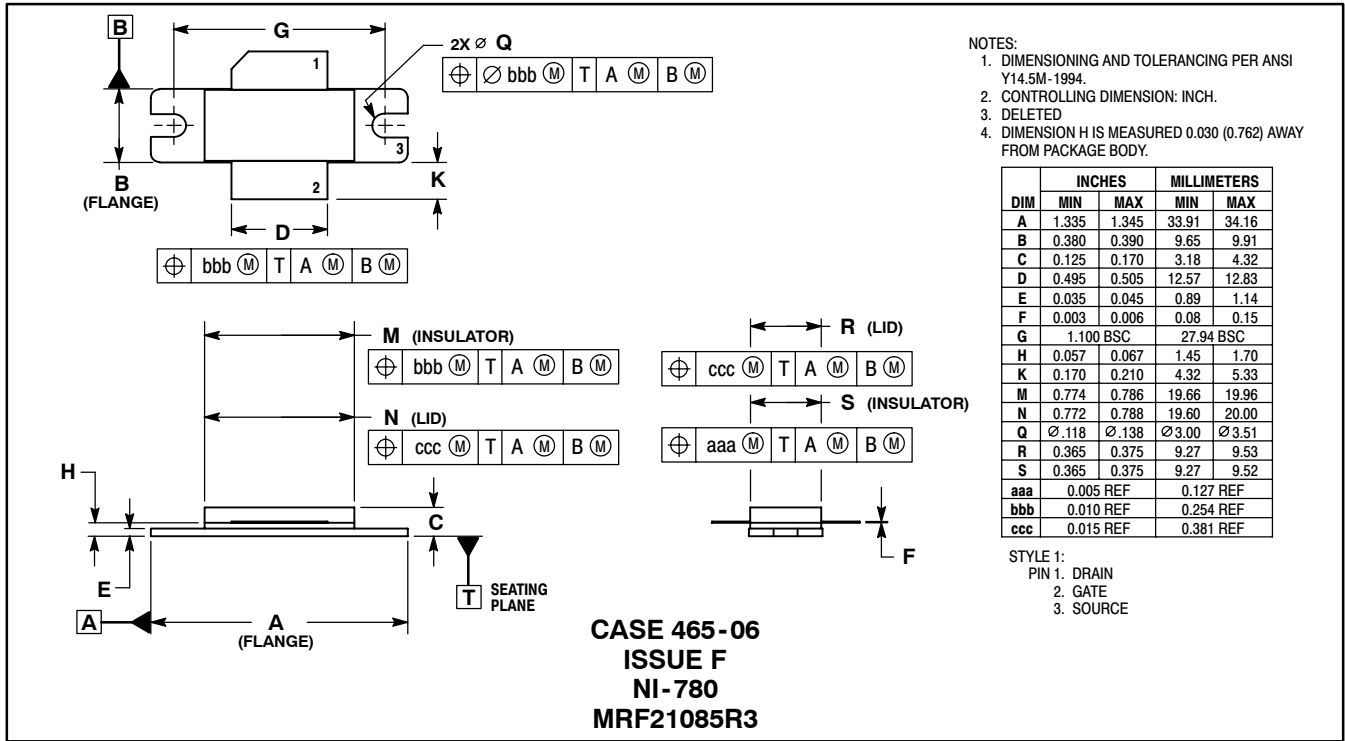
Figure 13. Series Equivalent Input and Output Impedance

NOTES

NOTES

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PACKAGE DIMENSIONS



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